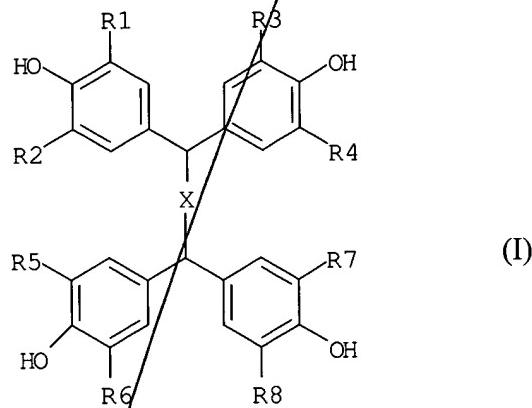


**AMENDMENT D NEW CLAIMS 23-34**

23. An epoxy resin composition comprising:
- a non-curing epoxy resin,
- a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin, and
- a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst,

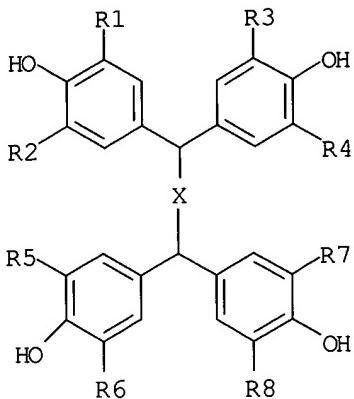


wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or a C<sub>1</sub>-C<sub>6</sub> alkoxy.

24. The epoxy resin composition according to claim 23, wherein the content of the tetrakisphenol compound represented in general formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

25. A method for curing an epoxy resin comprising a step of mixing a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst

with a non-curing epoxy resin,

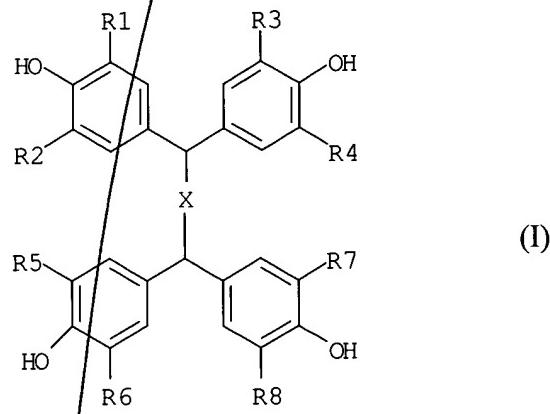


(I)

wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or a C<sub>1</sub>-C<sub>6</sub> alkoxy.

26. The method for curing an epoxy resin according to claim 25, wherein the content of the tetrakisphenol compound represented in general formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

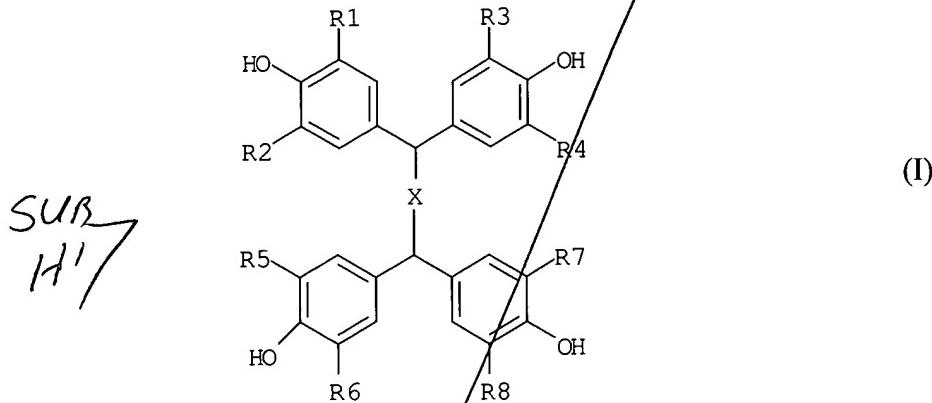
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27. A curative for epoxy resin, comprising a clathrate comprising:  
a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group to cure an epoxy resin,



(I)

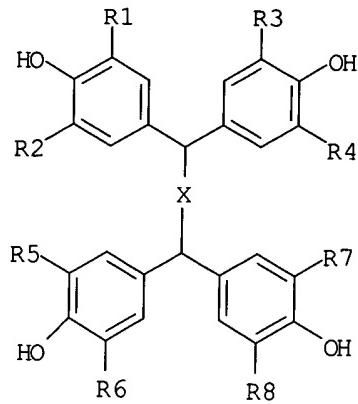
wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or a C<sub>1</sub>-C<sub>6</sub> alkoxy.

28. A curing accelerator for epoxy resin, comprising a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,



wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or a C<sub>1</sub>-C<sub>6</sub> alkoxy.

29. An epoxy resin composition, comprising a non-curing epoxy resin, and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin,

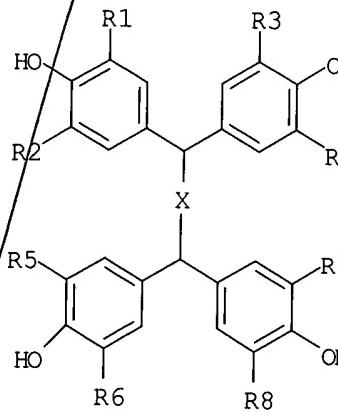


(I)

wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or a C<sub>1</sub>-C<sub>6</sub> alkoxy.

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30. An epoxy resin composition comprising a non-curing epoxy resin, and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin; and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,



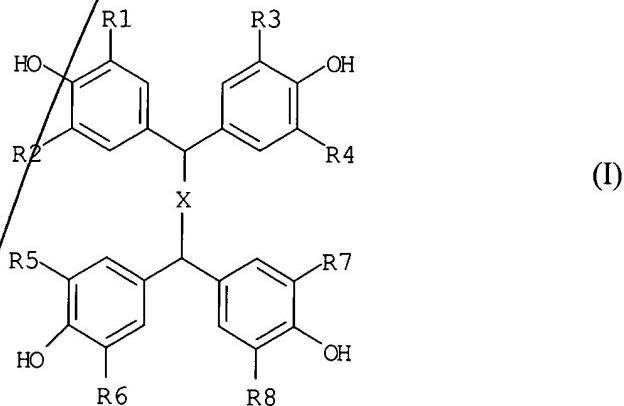
(I)

wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or a C<sub>1</sub>-C<sub>6</sub> alkoxy.

31. The epoxy resin composition according to claim 29 or 30, wherein the content of a tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

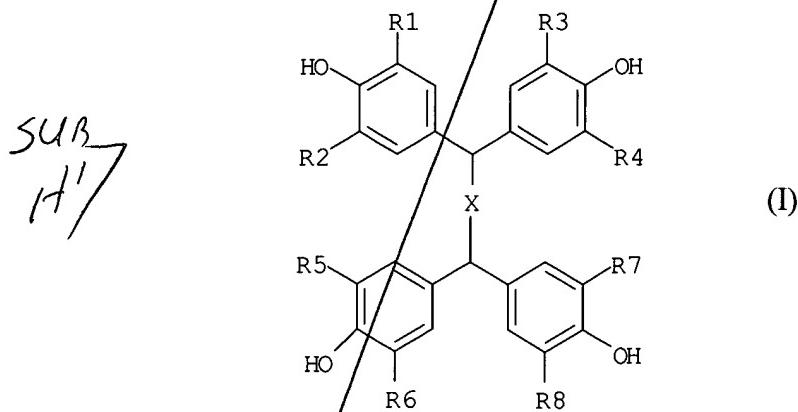
32. A method for curing an epoxy resin composition comprising the steps of:  
a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin is added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,

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wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or a C<sub>1</sub>-C<sub>6</sub> alkoxy.

33. A method for curing an epoxy resin composition comprising the steps of:  
a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a  
compound reacting with an epoxy group of the epoxy resin to cure the resin, and  
a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a  
compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy  
resin are added and mixed to a non-curing epoxy resin, and then the mixture is heated to a  
predetermined temperature,



wherein X represents  $(CH_2)_n$ , wherein n is 0, 1, 2 or 3, and R<sup>1</sup> to R<sup>8</sup> each represents  
hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C<sub>1</sub>-C<sub>6</sub> alkyl, a halogen or  
a C<sub>1</sub>-C<sub>6</sub> alkoxy.

34. The method for curing an epoxy resin composition according to claim 32 or 33,  
wherein the content of the tetrakisphenol compound represented by a general formula (I) in the  
clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.